**Product / Process Change Notice**

**Parts Affected:**

The 2N6059 NPN power darlington transistor wafer process.

**Extent of Change:**

Change in wafer fab, resulting in change in die size. The die size changed from 162 x 162 mils to 131 x 131 mils.

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure an undisrupted supply of product, a change in wafer fabrication site is being made for the referenced products. Product specifications, quality and reliability are not impacted by this change.

**Effect of Change:**

This change does not affect electrical device characteristics.

**Qualification:**

|  |  |  |  |
| --- | --- | --- | --- |
| **Test** | **Condition** | **Duration** | **Failure rate** |
| **High Temperature**  **Storage Life** | Ta=150°C | 168 Hours | 0/22 |
| **Low Temperature**  **Storage Life** | Ta=-65°C | 168 Hours | 0/22 |
| **High Temperature Reverse Bias** | Ta=150℃, 80% Rated Voltage | 168 Hours | 0/22 |
| **Operating Life** | Ta=-65°C, Tc=110°C | 168 Hours | 0/22 |
| **Pressure Cooker** | Ta=119.6°C, P=2atm | 144 Hours | 0/22 |
| **Temperature Cycling**  **(Air-to-Air)** | Ta= -65 30min  Ta= +150 30min  Transfer time less than 1min. | 50 Cycles | 0/22 |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Part Numbers Affected:**

|  |  |  |
| --- | --- | --- |
| BDX85 | MJ1000 | SE9303 |
| BDX85A | MJ1001 | SE9304 |
| BDX85B | MJ3000 | SE9305 |
| BDX85C | MJ3001 | 2N6055 |
| BDX87 | PMD10K40 | 2N6056 |
| BDX87A | PMD10K60 | 2N6057 |
| BDX87B | PMD10K80 | 2N6058 |
| BDX87C | PMD10K100 | 2N6059 |
| CEN1092 | PMD12K40 | 2N6383 |
| CEN1391 | PMD12K60 | 2N6384 |
| CEN992 | PMD12K80 | 2N6385 |
|  | PMD12K100 |  |

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

|  |  |
| --- | --- |
| Company Name: |  |
| Address: |  |
|  |
|  |
| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |